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#### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

E·XFI

Product Status	Active
Core Processor	508
Core Size	8-Bit
Speed	40MHz
Connectivity	CANbus, I <sup>2</sup> C, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	39
Program Memory Size	48KB (48K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc9s08dv48clf

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



# Chapter 3 Modes of Operation

# 3.1 Introduction

The operating modes of the MC9S08DV60 Series are described in this chapter. Entry into each mode, exit from each mode, and functionality while in each of the modes are described.

# 3.2 Features

- Active background mode for code development
- Wait mode CPU shuts down to conserve power; system clocks are running and full regulation is maintained
- Stop modes System clocks are stopped and voltage regulator is in standby
  - Stop3 All internal circuits are powered for fast recovery
  - Stop2 Partial power down of internal circuits; RAM content is retained

# 3.3 Run Mode

This is the normal operating mode for the MC9S08DV60 Series. This mode is selected when the BKGD/MS pin is high at the rising edge of reset. In this mode, the CPU executes code from internal memory with execution beginning at the address fetched from memory at 0xFFFE–0xFFFF after reset.

# 3.4 Active Background Mode

The active background mode functions are managed through the background debug controller (BDC) in the HCS08 core. The BDC, together with the on-chip debug module (DBG), provide the means for analyzing MCU operation during software development.

Active background mode is entered in any of five ways:

- When the BKGD/MS pin is low at the rising edge of reset
- When a BACKGROUND command is received through the BKGD/MS pin
- When a BGND instruction is executed
- When encountering a BDC breakpoint
- When encountering a DBG breakpoint

After entering active background mode, the CPU is held in a suspended state waiting for serial background commands rather than executing instructions from the user application program.



To maintain I/O states for pins that were configured as general-purpose I/O before entering stop2, the user must restore the contents of the I/O port registers, which have been saved in RAM, to the port registers before writing to the PPDACK bit. If the port registers are not restored from RAM before writing to PPDACK, then the pins will switch to their reset states when PPDACK is written.

For pins that were configured as peripheral I/O, the user must reconfigure the peripheral module that interfaces to the pin before writing to the PPDACK bit. If the peripheral module is not enabled before writing to PPDACK, the pins will be controlled by their associated port control registers when the I/O latches are opened.

## 3.6.3 On-Chip Peripheral Modules in Stop Modes

When the MCU enters any stop mode, system clocks to the internal peripheral modules are stopped. Even in the exception case (ENBDM = 1), where clocks to the background debug logic continue to operate, clocks to the peripheral systems are halted to reduce power consumption. Refer to Section 3.6.2, "Stop2 Mode" and Section 3.6.1, "Stop3 Mode" for specific information on system behavior in stop modes.

Poriphoral	Mode				
renpilerai	Stop2	Stop3			
CPU	Off	Standby			
RAM	Standby	Standby			
Flash	Off	Standby			
Parallel Port Registers	Off	Standby			
ACMP	Off	Off			
ADC	Off	Optionally On <sup>1</sup>			
IIC	Off	Standby			
MCG	Off	Optionally On <sup>2</sup>			
MSCAN	Off	Standby			
RTC	Optionally On <sup>3</sup>	Optionally On <sup>3</sup>			
SCI	Off	Standby			
SPI	Off	Standby			
ТРМ	Off	Standby			
Voltage Regulator	Off	Optionally On <sup>4</sup>			
XOSC	Off	Optionally On <sup>5</sup>			
I/O Pins	States Held	States Held			
BDM	Off <sup>6</sup>	Optionally On			
LVD/LVW	Off <sup>7</sup>	Optionally On			

<sup>1</sup> Requires the asynchronous ADC clock and LVD to be enabled, else in standby.

<sup>2</sup> IRCLKEN and IREFSTEN set in MCGC1, else in standby.

<sup>3</sup> Requires the RTC to be enabled, else in standby.

<sup>4</sup> Requires the LVD or BDC to be enabled.



Chapter 4 Memory

Table 4-2. Direct-Page Register Summary (Sheet 2 of 3)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x00 <b>28</b>	TPM1C1SC	CH1F	CH1IE	MS1B	MS1A	ELS1B	ELS1A	0	0
0x00 <b>29</b>	TPM1C1VH	Bit 15	14	13	12	11	10	9	Bit 8
0x00 <b>2A</b>	TPM1C1VL	Bit 7	6	5	4	3	2	1	Bit 0
0x00 <b>2B</b>	TPM1C2SC	CH2F	CH2IE	MS2B	MS2A	ELS2B	ELS2A	0	0
0x00 <b>2C</b>	TPM1C2VH	Bit 15	14	13	12	11	10	9	Bit 8
0x00 <b>2D</b>	TPM1C2VL	Bit 7	6	5	4	3	2	1	Bit 0
0x00 <b>2E</b>	TPM1C3SC	CH3F	CH3IE	MS3B	MS3A	ELS3B	ELS3A	0	0
0x00 <b>2F</b>	TPM1C3VH	Bit 15	14	13	12	11	10	9	Bit 8
0x00 <b>30</b>	TPM1C3VL	Bit 7	6	5	4	3	2	1	Bit 0
0x00 <b>31</b>	TPM1C4SC	CH4F	CH4IE	MS4B	MS4A	ELS4B	ELS4A	0	0
0x00 <b>32</b>	TPM1C4VH	Bit 15	14	13	12	11	10	9	Bit 8
0x00 <b>33</b>	TPM1C4VL	Bit 7	6	5	4	3	2	1	Bit 0
0x00 <b>34</b>	TPM1C5SC	CH5F	CH5IE	MS5B	MS5A	ELS5B	ELS5A	0	0
0x00 <b>35</b>	TPM1C5VH	Bit 15	14	13	12	11	10	9	Bit 8
0x00 <b>36</b>	TPM1C5VL	Bit 7	6	5	4	3	2	1	Bit 0
0x00 <b>37</b>	Reserved		—	—	_	_	—	—	—
0x00 <b>38</b>	SCI1BDH	LBKDIE	RXEDGIE	0	SBR12	SBR11	SBR10	SBR9	SBR8
0x00 <b>39</b>	SCI1BDL	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
0x00 <b>3A</b>	SCI1C1	LOOPS	SCISWAI	RSRC	М	WAKE	ILT	PE	PT
0x00 <b>3B</b>	SCI1C2	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
0x00 <b>3C</b>	SCI1S1	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
0x00 <b>3D</b>	SCI1S2	LBKDIF	RXEDGIF	0	RXINV	RWUID	BRK13	LBKDE	RAF
0x00 <b>3E</b>	SCI1C3	R8	Т8	TXDIR	TXINV	ORIE	NEIE	FEIE	PEIE
0x00 <b>3F</b>	SCI1D	Bit 7	6	5	4	3	2	1	Bit 0
0x00 <b>40</b>	SCI2BDH	LBKDIE	RXEDGIE	0	SBR12	SBR11	SBR10	SBR9	SBR8
0x00 <b>41</b>	SCI2BDL	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
0x00 <b>42</b>	SCI2C1	LOOPS	SCISWAI	RSRC	М	WAKE	ILT	PE	PT
0x00 <b>43</b>	SCI2C2	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
0x00 <b>44</b>	SCI2S1	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
0x00 <b>45</b>	SCI2S2	LBKDIF	RXEDGIF	0	RXINV	RWUID	BRK13	LBKDE	RAF
0x00 <b>46</b>	SCI2C3	R8	Т8	TXDIR	TXINV	ORIE	NEIE	FEIE	PEIE
0x00 <b>47</b>	SCI2D	Bit 7	6	5	4	3	2	1	Bit 0
0x00 <b>48</b>	MCGC1	CL	KS		RDIV		IREFS	IRCLKEN	IREFSTEN
0x00 <b>49</b>	MCGC2	BC	NV	RANGE	HGO	IGO LP		ERCLKEN	EREFSTEN
0x00 <b>4A</b>	MCGTRM				TR	MIM			
0x00 <b>4B</b>	MCGSC	LOLS	LOCK	PLLST	IREFST	CL	(ST	OSCINIT	FTRIM
0x00 <b>4C</b>	MCGC3	LOLIE	PLLS	CME	0		VE	DIV	
0x004 <b>D</b> – 0x004 <b>F</b>	Reserved	—	—	_	—	—	_	—	—

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### Table 5-1. Vector Summary<sup>1</sup>

Vector	Address	Vector	Modulo	Sourco	Enable	Description
No.	(High/Low)	Name	wodule	Source	Eliable	Description
31	0xFFC0/0xFFC1	Vacmp2	ACMP2	ACF	ACIE	Analog comparator 2
30	0xFFC2/0xFFC3	Vacmp1	ACMP1	ACF	ACIE	Analog comparator 1
29	0xFFC4/0xFFC5	Vcantx	MSCAN	TXE[2:0]	TXEIE[2:0]	CAN transmit
28	0xFFC6/0xFFC7	Vcanrx	MSCAN	RXF	RXFIE	CAN receive
27	0xFFC8/0xFFC9	Vcanerr	MSCAN	CSCIF, OVRIF	CSCIE, OVRIE	CAN errors
26	0xFFCA/0xFFCB	Vcanwu	MSCAN	WUPIF	WUPIE	CAN wake-up
25	0xFFCC/0xFFCD	Vrtc	RTC	RTIF	RTIE	Real-time interrupt
24	0xFFCE/0xFFCF	Viic	IIC	IICIS	IICIE	IIC control
23	0xFFD0/0xFFD1	Vadc	ADC	COCO	AIEN	ADC
22	0xFFD2/0xFFD3	Vport	Port A,B,D	PTAIF, PTBIF, PTDIF	PTAIE, PTBIE, PTDIE	Port Pins
21	0xFFD4/0xFFD5	Vsci2tx	SCI2	TDRE, TC	TIE, TCIE	SCI2 transmit
20	0xFFD6/0xFFD7	Vsci2rx	SCI2	IDLE, LBKDIF, RDRF, RXEDGIF	ILIE, LBKDIE, RIE, RXEDGIE	SCI2 receive
19	0xFFD8/0xFFD9	Vsci2err	SCI2	OR, NF FE, PF	ORIE, NFIE, FEIE, PFIE	SCI2 error
18	0xFFDA/0xFFDB	Vsci1tx	SCI1	TDRE, TC	TIE, TCIE	SCI1 transmit
17	0xFFDC/0xFFDD	Vsci1rx	SCI1	IDLE, LBKDIF, RDRF, RXEDGIF	ILIE, LBKDIE, RIE, RXEDGIE	SCI1 receive
16	0xFFDE/0xFFDF	Vsci1err	SCI1	OR, NF, FE, PF	ORIE, NFIE, FEIE, PFIE	SCI1 error
15	0xFFE0/0xFFE1	Vspi	SPI	SPIF, MODF, SPTEF	SPIE, SPIE, SPTIE	SPI
14	0xFFE2/0xFFE3	Vtpm2ovf	TPM2	TOF	TOIE	TPM2 overflow
13	0xFFE4/0xFFE5	Vtpm2ch1	TPM2	CH1F	CH1IE	TPM2 channel 1
12	0xFFE6/0xFFE7	Vtpm2ch0	TPM2	CH0F	CHOIE	TPM2 channel 0
11	0xFFE8/0xFFE9	Vtpm1ovf	TPM1	TOF	TOIE	TPM1 overflow
10	0xFFEA/0xFFEB	Vtpm1ch5	TPM1	CH5F	CH5IE	TPM1 channel 5
9	0xFFEC/0xFFED	Vtpm1ch4	TPM1	CH4F	CH4IE	TPM1 channel 4
8	0xFFEE/0xFFEF	Vtpm1ch3	TPM1	CH3F	CH3IE	TPM1 channel 3
7	0xFFF0/0xFFF1	Vtpm1ch2	TPM1	CH2F	CH2IE	TPM1 channel 2
6	0xFFF2/0xFFF3	Vtpm1ch1	TPM1	CH1F	CH1IE	TPM1 channel 1
5	0xFFF4/0xFFF5	Vtpm1ch0	TPM1	CH0F	CH0IE	TPM1 channel 0
4	0xFFF6/0xFFF7	Vlol	MCG	LOLS	LOLIE	MCG loss of lock
3	0xFFF8/0xFFF9	Vlvd	System control	LVWF	LVWIE	Low-voltage warning
2	0xFFFA/0xFFFB	Virq	IRQ	IRQF	IRQIE	IRQ pin
1	0xFFFC/0xFFFD	Vswi	Core	SWI Instruction	—	Software interrupt
0	0xFFFE/0xFFFF	Vreset	System control	COP, LOC, LVD, RESET, ILOP, ILAD, POR	COPE CME LVDRE — — — —	Watchdog timer Loss-of-clock Low-voltage detect External pin Illegal opcode Illegal address Power-on-reset
				BDFR	_	BDM-forced reset

<sup>1</sup> Vector priority is shown from lowest (first row) to highest (last row). For example, Vreset is the highest priority vector.



Chapter 6 Parallel Input/Output Control

# 6.5.3.5 Port C Drive Strength Selection Register (PTCDS)

_	7	6	5	4	3	2	1	0
R W	PTCDS7	PTCDS6	PTCDS5	PTCDS4	PTCDS3	PTCDS2	PTCDS1	PTCDS0
Reset:	0	0	0	0	0	0	0	0

Figure 6-23. Drive Strength Selection for Port C Register (PTCDS)

### Table 6-21. PTCDS Register Field Descriptions

Field	Description
7:0 PTCDS[7:0]	<ul> <li>Output Drive Strength Selection for Port C Bits — Each of these control bits selects between low and high output drive for the associated PTC pin. For port C pins that are configured as inputs, these bits have no effect.</li> <li>0 Low output drive strength selected for port C bit n.</li> <li>1 High output drive strength selected for port C bit n.</li> </ul>



Chapter 6 Parallel Input/Output Control



# 7.2.3 Stack Pointer (SP)

This 16-bit address pointer register points at the next available location on the automatic last-in-first-out (LIFO) stack. The stack may be located anywhere in the 64-Kbyte address space that has RAM and can be any size up to the amount of available RAM. The stack is used to automatically save the return address for subroutine calls, the return address and CPU registers during interrupts, and for local variables. The AIS (add immediate to stack pointer) instruction adds an 8-bit signed immediate value to SP. This is most often used to allocate or deallocate space for local variables on the stack.

SP is forced to 0x00FF at reset for compatibility with the earlier M68HC05 Family. HCS08 programs normally change the value in SP to the address of the last location (highest address) in on-chip RAM during reset initialization to free up direct page RAM (from the end of the on-chip registers to 0x00FF).

The RSP (reset stack pointer) instruction was included for compatibility with the M68HC05 Family and is seldom used in new HCS08 programs because it only affects the low-order half of the stack pointer.

# 7.2.4 Program Counter (PC)

The program counter is a 16-bit register that contains the address of the next instruction or operand to be fetched.

During normal program execution, the program counter automatically increments to the next sequential memory location every time an instruction or operand is fetched. Jump, branch, interrupt, and return operations load the program counter with an address other than that of the next sequential location. This is called a change-of-flow.

During reset, the program counter is loaded with the reset vector that is located at 0xFFFE and 0xFFFF. The vector stored there is the address of the first instruction that will be executed after exiting the reset state.

# 7.2.5 Condition Code Register (CCR)

The 8-bit condition code register contains the interrupt mask (I) and five flags that indicate the results of the instruction just executed. Bits 6 and 5 are set permanently to 1. The following paragraphs describe the functions of the condition code bits in general terms. For a more detailed explanation of how each instruction sets the CCR bits, refer to the *HCS08 Family Reference Manual, volume 1*, Freescale Semiconductor document order number HCS08RMv1.



### 8.5.2.3 Example #3: Moving from BLPI to FEE Mode: External Crystal = 4 MHz, Bus Frequency = 16 MHz

In this example, the MCG will move through the proper operational modes from BLPI mode at a 16 kHz bus frequency running off of the internal reference clock (see previous example) to FEE mode using a 4 MHz crystal configured for a 16 MHz bus frequency. First, the code sequence will be described. Then a flowchart will be included which illustrates the sequence.

- 1. First, BLPI must transition to FBI mode.
  - a) MCGC2 = 0x00 (%00000000)
    - LP (bit 3) in MCGSC is 0
  - b) Optionally, loop until LOCK (bit 6) in the MCGSC is set, indicating that the FLL has acquired lock. Although the FLL is bypassed in FBI mode, it is still enabled and running.
- 2. Next, FBI will transition to FEE mode.
  - a) MCGC2 = 0x36 (%00110110)
    - RANGE (bit 5) set to 1 because the frequency of 4 MHz is within the high frequency range
    - HGO (bit 4) set to 1 to configure external oscillator for high gain operation
    - EREFS (bit 2) set to 1, because a crystal is being used
    - ERCLKEN (bit 1) set to 1 to ensure the external reference clock is active
  - b) Loop until OSCINIT (bit 1) in MCGSC is 1, indicating the crystal selected by the EREFS bit has been initialized.
  - c) MCGC1 = 0x38 (%00111000)
    - CLKS (bits 7 and 6) set to %00 in order to select the output of the FLL as system clock source
    - RDIV (bits 5-3) set to %111, or divide-by-128 because 4 MHz / 128 = 31.25 kHz which is in the 31.25 kHz to 39.0625 kHz range required by the FLL
    - IREFS (bit 1) cleared to 0, selecting the external reference clock
  - d) Loop until IREFST (bit 4) in MCGSC is 0, indicating the external reference clock is the current source for the reference clock
  - e) Optionally, loop until LOCK (bit 6) in the MCGSC is set, indicating that the FLL has reacquired lock.
  - f) Loop until CLKST (bits 3 and 2) in MCGSC are %00, indicating that the output of the FLL is selected to feed MCGOUT



# 10.2.1 Analog Power (V<sub>DDAD</sub>)

The ADC analog portion uses  $V_{DDAD}$  as its power connection. In some packages,  $V_{DDAD}$  is connected internally to  $V_{DD}$ . If externally available, connect the  $V_{DDAD}$  pin to the same voltage potential as  $V_{DD}$ . External filtering may be necessary to ensure clean  $V_{DDAD}$  for good results.

# 10.2.2 Analog Ground (V<sub>SSAD</sub>)

The ADC analog portion uses  $V_{SSAD}$  as its ground connection. In some packages,  $V_{SSAD}$  is connected internally to  $V_{SS}$ . If externally available, connect the  $V_{SSAD}$  pin to the same voltage potential as  $V_{SS}$ .

## 10.2.3 Voltage Reference High (V<sub>REFH</sub>)

 $V_{REFH}$  is the high reference voltage for the converter. In some packages,  $V_{REFH}$  is connected internally to  $V_{DDAD}$ . If externally available,  $V_{REFH}$  may be connected to the same potential as  $V_{DDAD}$  or may be driven by an external source between the minimum  $V_{DDAD}$  spec and the  $V_{DDAD}$  potential ( $V_{REFH}$  must never exceed  $V_{DDAD}$ ).

## 10.2.4 Voltage Reference Low (V<sub>REFL</sub>)

 $V_{REFL}$  is the low-reference voltage for the converter. In some packages,  $V_{REFL}$  is connected internally to  $V_{SSAD}$ . If externally available, connect the  $V_{REFL}$  pin to the same voltage potential as  $V_{SSAD}$ .

## 10.2.5 Analog Channel Inputs (ADx)

The ADC module supports up to 28 separate analog inputs. An input is selected for conversion through the ADCH channel select bits.

# **10.3 Register Definition**

These memory-mapped registers control and monitor operation of the ADC:

- Status and control register, ADCSC1
- Status and control register, ADCSC2
- Data result registers, ADCRH and ADCRL
- Compare value registers, ADCCVH and ADCCVL
- Configuration register, ADCCFG
- Pin control registers, APCTL1, APCTL2, APCTL3

## 10.3.1 Status and Control Register 1 (ADCSC1)

This section describes the function of the ADC status and control register (ADCSC1). Writing ADCSC1 aborts the current conversion and initiates a new conversion (if the ADCH bits are equal to a value other than all 1s).



Field	Description
7 ADPC15	ADC Pin Control 15. ADPC15 controls the pin associated with channel AD15. 0 AD15 pin I/O control enabled 1 AD15 pin I/O control disabled
6 ADPC14	ADC Pin Control 14. ADPC14 controls the pin associated with channel AD14. 0 AD14 pin I/O control enabled 1 AD14 pin I/O control disabled
5 ADPC13	ADC Pin Control 13. ADPC13 controls the pin associated with channel AD13. 0 AD13 pin I/O control enabled 1 AD13 pin I/O control disabled
4 ADPC12	ADC Pin Control 12. ADPC12 controls the pin associated with channel AD12. 0 AD12 pin I/O control enabled 1 AD12 pin I/O control disabled
3 ADPC11	ADC Pin Control 11. ADPC11 controls the pin associated with channel AD11. 0 AD11 pin I/O control enabled 1 AD11 pin I/O control disabled
2 ADPC10	ADC Pin Control 10. ADPC10 controls the pin associated with channel AD10. 0 AD10 pin I/O control enabled 1 AD10 pin I/O control disabled
1 ADPC9	ADC Pin Control 9. ADPC9 controls the pin associated with channel AD9. 0 AD9 pin I/O control enabled 1 AD9 pin I/O control disabled
0 ADPC8	ADC Pin Control 8. ADPC8 controls the pin associated with channel AD8. 0 AD8 pin I/O control enabled 1 AD8 pin I/O control disabled

### Table 10-11. APCTL2 Register Field Descriptions

# 10.3.10 Pin Control 3 Register (APCTL3)

APCTL3 controls channels 16–23 of the ADC module.



Figure 10-12. Pin Control 3 Register (APCTL3)



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Chapter 10 Analog-to-Digital Converter (S08ADC12V1)
```

ALTCLK for this MCU. Consult the module introduction for information on ALTCLK specific to this MCU.

A conversion complete event sets the COCO and generates an ADC interrupt to wake the MCU from wait mode if the ADC interrupt is enabled (AIEN = 1).

# 10.4.7 MCU Stop3 Mode Operation

Stop mode is a low power-consumption standby mode during which most or all clock sources on the MCU are disabled.

# 10.4.7.1 Stop3 Mode With ADACK Disabled

If the asynchronous clock, ADACK, is not selected as the conversion clock, executing a stop instruction aborts the current conversion and places the ADC in its idle state. The contents of ADCRH and ADCRL are unaffected by stop3 mode. After exiting from stop3 mode, a software or hardware trigger is required to resume conversions.

# 10.4.7.2 Stop3 Mode With ADACK Enabled

If ADACK is selected as the conversion clock, the ADC continues operation during stop3 mode. For guaranteed ADC operation, the MCU's voltage regulator must remain active during stop3 mode. Consult the module introduction for configuration information for this MCU.

If a conversion is in progress when the MCU enters stop3 mode, it continues until completion. Conversions can be initiated while the MCU is in stop3 mode by means of the hardware trigger or if continuous conversions are enabled.

A conversion complete event sets the COCO and generates an ADC interrupt to wake the MCU from stop3 mode if the ADC interrupt is enabled (AIEN = 1).

### NOTE

The ADC module can wake the system from low-power stop and cause the MCU to begin consuming run-level currents without generating a system level interrupt. To prevent this scenario, software should ensure the data transfer blocking mechanism (discussed in Section 10.4.4.2, "Completing Conversions) is cleared when entering stop3 and continuing ADC conversions.

# 10.4.8 MCU Stop2 Mode Operation

The ADC module is automatically disabled when the MCU enters stop2 mode. All module registers contain their reset values following exit from stop2. Therefore, the module must be re-enabled and re-configured following exit from stop2.



# Chapter 11 Inter-Integrated Circuit (S08IICV2)

# 11.1 Introduction

The inter-integrated circuit (IIC) provides a method of communication between a number of devices. The interface is designed to operate up to 100 kbps with maximum bus loading and timing. The device is capable of operating at higher baud rates, up to a maximum of clock/20, with reduced bus loading. The maximum communication length and the number of devices that can be connected are limited by a maximum bus capacitance of 400 pF.

All MC9S08DV60 Series MCUs feature the IIC, as shown in the following block diagram.

### NOTE

Drive strength must be disabled (DSE=0) for the IIC pins when using the IIC module for correct operation.





### Figure 12-10. MSCAN Transmitter Flag Register (CANTFLG)

#### NOTE

The CANTFLG register is held in the reset state when the initialization mode is active (INITRQ = 1 and INITAK = 1). This register is writable when not in initialization mode (INITRQ = 0 and INITAK = 0).

Read: Anytime

Write: Anytime for TXEx flags when not in initialization mode; write of 1 clears flag, write of 0 is ignored

Field	Description
2:0 TXE[2:0]	Transmitter Buffer Empty — This flag indicates that the associated transmit message buffer is empty, and thus not scheduled for transmission. The CPU must clear the flag after a message is set up in the transmit buffer and is due for transmission. The MSCAN sets the flag after the message is sent successfully. The flag is also set by the MSCAN when the transmission request is successfully aborted due to a pending abort request (see Section 12.3.8, "MSCAN Transmitter Message Abort Request Register (CANTARQ)"). If not masked, a transmit interrupt is pending while this flag is set. Clearing a TXEx flag also clears the corresponding ABTAKx (see Section 12.3.9, "MSCAN Transmitter Message Abort Acknowledge Register (CANTAAK)"). When a TXEx flag is set, the corresponding ABTRQx bit is cleared (see Section 12.3.8, "MSCAN Transmitter Message Abort Request Register (CANTARQ)"). When listen-mode is active (see Section 12.3.2, "MSCAN Control Register 1 (CANCTL1)") the TXEx flags cannot be cleared and no transmission is started. Read and write accesses to the transmit buffer are blocked, if the corresponding TXEx bit is cleared (TXEx = 0) and the buffer is scheduled for transmission. 0 The associated message buffer is full (loaded with a message due for transmission) 1 The associated message buffer is empty (not scheduled)

#### Table 12-11. CANTFLG Register Field Descriptions

# 12.3.7 MSCAN Transmitter Interrupt Enable Register (CANTIER)

This register contains the interrupt enable bits for the transmit buffer empty interrupt flags.





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Table 12-30. IDR1	<b>Register Field</b>	Descriptions
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Field	Description							
7:5 ID[2:0]	Standard Fo most significa identifier is d	<b>Standard Format Identifier</b> — The identifiers consist of 11 bits (ID[10:0]) for the standard format. ID10 is the most significant bit and is transmitted first on the CAN bus during the arbitration procedure. The priority of an identifier is defined to be highest for the smallest binary number. See also ID bits in Table 12-29.						
4 RTR	Remote Transmission Request — This flag reflects the status of the Remote Transmission Request bit in the CAN frame. In the case of a receive buffer, it indicates the status of the received frame and supports the transmission of an answering frame in software. In the case of a transmit buffer, this flag defines the setting of the RTR bit to be sent.         0       Data frame         1       Remote frame							
3 IDE	<ul> <li>ID Extended — This flag indicates whether the extended or standard identifier format is applied in this buffer. In the case of a receive buffer, the flag is set as received and indicates to the CPU how to process the buffer identifier registers. In the case of a transmit buffer, the flag indicates to the MSCAN what type of identifier to send.</li> <li>0 Standard format (11 bit)</li> <li>1 Extended format (29 bit)</li> </ul>							
R								
vv								



# 12.4.3 Data Segment Registers (DSR0-7)

The eight data segment registers, each with bits DB[7:0], contain the data to be transmitted or received. The number of bytes to be transmitted or received is determined by the data length code in the corresponding DLR register.



- Four identifier acceptance filters, each to be applied to
  - a) the 14 most significant bits of the extended identifier plus the SRR and IDE bits of CAN 2.0B messages or
  - b) the 11 bits of the standard identifier, the RTR and IDE bits of CAN 2.0A/B messages. Figure 12-40 shows how the first 32-bit filter bank (CANIDAR0–CANIDA3, CANIDMR0–3CANIDMR) produces filter 0 and 1 hits. Similarly, the second filter bank (CANIDAR4–CANIDAR7, CANIDMR4–CANIDMR7) produces filter 2 and 3 hits.
- Eight identifier acceptance filters, each to be applied to the first 8 bits of the identifier. This mode implements eight independent filters for the first 8 bits of a CAN 2.0A/B compliant standard identifier or a CAN 2.0B compliant extended identifier. Figure 12-41 shows how the first 32-bit filter bank (CANIDAR0–CANIDAR3, CANIDMR0–CANIDMR3) produces filter 0 to 3 hits. Similarly, the second filter bank (CANIDAR4–CANIDAR7, CANIDMR7, CANIDMR7) produces filter 4 to 7 hits.
- Closed filter. No CAN message is copied into the foreground buffer RxFG, and the RXF flag is never set.



Figure 12-39. 32-bit Maskable Identifier Acceptance Filter



## 12.5.7.1 Description of Interrupt Operation

The MSCAN supports four interrupt vectors (see Table 12-37), any of which can be individually masked (for details see sections from Section 12.3.5, "MSCAN Receiver Interrupt Enable Register (CANRIER)," to Section 12.3.7, "MSCAN Transmitter Interrupt Enable Register (CANTIER)").

### NOTE

The dedicated interrupt vector addresses are defined in the Resets and Interrupts chapter.

Interrupt Source	CCR Mask	Local Enable
Wake-Up Interrupt (WUPIF)	l bit	CANRIER (WUPIE)
Error Interrupts Interrupt (CSCIF, OVRIF)	l bit	CANRIER (CSCIE, OVRIE)
Receive Interrupt (RXF)	l bit	CANRIER (RXFIE)
Transmit Interrupts (TXE[2:0])	l bit	CANTIER (TXEIE[2:0])

Table 12-37. Interrupt Vectors

### 12.5.7.2 Transmit Interrupt

At least one of the three transmit buffers is empty (not scheduled) and can be loaded to schedule a message for transmission. The TXEx flag of the empty message buffer is set.

### 12.5.7.3 Receive Interrupt

A message is successfully received and shifted into the foreground buffer (RxFG) of the receiver FIFO. This interrupt is generated immediately after receiving the EOF symbol. The RXF flag is set. If there are multiple messages in the receiver FIFO, the RXF flag is set as soon as the next message is shifted to the foreground buffer.

### 12.5.7.4 Wake-Up Interrupt

A wake-up interrupt is generated if activity on the CAN bus occurs during MSCAN internal sleep mode. WUPE (see Section 12.3.1, "MSCAN Control Register 0 (CANCTL0)") must be enabled.

## 12.5.7.5 Error Interrupt

An error interrupt is generated if an overrun of the receiver FIFO, error, warning, or bus-off condition occurrs. Section 12.3.4.1, "MSCAN Receiver Flag Register (CANRFLG) indicates one of the following conditions:

- **Overrun** An overrun condition of the receiver FIFO as described in Section 12.5.2.3, "Receive Structures," occurred.
- CAN Status Change The actual value of the transmit and receive error counters control the CAN bus state of the MSCAN. As soon as the error counters skip into a critical range (Tx/Rx-warning, Tx/Rx-error, bus-off) the MSCAN flags an error condition. The status change, which caused the error condition, is indicated by the TSTAT and RSTAT flags (see



Field	Description
1 LBKDE	<ul> <li>LIN Break Detection Enable— LBKDE is used to select a longer break character detection length. While LBKDE is set, framing error (FE) and receive data register full (RDRF) flags are prevented from setting.</li> <li>0 Break character is detected at length of 10 bit times (11 if M = 1).</li> <li>1 Break character is detected at length of 11 bit times (12 if M = 1).</li> </ul>
0 RAF	<ul> <li>Receiver Active Flag — RAF is set when the SCI receiver detects the beginning of a valid start bit, and RAF is cleared automatically when the receiver detects an idle line. This status flag can be used to check whether an SCI character is being received before instructing the MCU to go to stop mode.</li> <li>0 SCI receiver idle waiting for a start bit.</li> <li>1 SCI receiver active (RxD input not idle).</li> </ul>

#### Table 14-7. SCIxS2 Field Descriptions (continued)

<sup>1</sup> Setting RXINV inverts the RxD input for all cases: data bits, start and stop bits, break, and idle.

When using an internal oscillator in a LIN system, it is necessary to raise the break detection threshold by one bit time. Under the worst case timing conditions allowed in LIN, it is possible that a 0x00 data character can appear to be 10.26 bit times long at a slave which is running 14% faster than the master. This would trigger normal break detection circuitry which is designed to detect a 10 bit break symbol. When the LBKDE bit is set, framing errors are inhibited and the break detection threshold changes from 10 bits to 11 bits, preventing false detection of a 0x00 data character as a LIN break symbol.

# 14.2.6 SCI Control Register 3 (SCIxC3)



### Figure 14-10. SCI Control Register 3 (SCIxC3)

Field	Description
7 R8	<b>Ninth Data Bit for Receiver</b> — When the SCI is configured for 9-bit data ( $M = 1$ ), R8 can be thought of as a ninth receive data bit to the left of the MSB of the buffered data in the SCIxD register. When reading 9-bit data, read R8 before reading SCIxD because reading SCIxD completes automatic flag clearing sequences which could allow R8 and SCIxD to be overwritten with new data.
6 T8	<b>Ninth Data Bit for Transmitter</b> — When the SCI is configured for 9-bit data (M = 1), T8 may be thought of as a ninth transmit data bit to the left of the MSB of the data in the SCIxD register. When writing 9-bit data, the entire 9-bit value is transferred to the SCI shift register after SCIxD is written so T8 should be written (if it needs to change from its previous value) before SCIxD is written. If T8 does not need to change in the new value (such as when it is used to generate mark or space parity), it need not be written each time SCIxD is written.
5 TXDIR	<b>TxD Pin Direction in Single-Wire Mode</b> — When the SCI is configured for single-wire half-duplex operation(LOOPS = RSRC = 1), this bit determines the direction of data at the TxD pin.0TxD pin is an input in single-wire mode.1TxD pin is an output in single-wire mode.

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#### Chapter 14 Serial Communications Interface (S08SCIV4)

Instead of hardware interrupts, software polling may be used to monitor the TDRE and TC status flags if the corresponding TIE or TCIE local interrupt masks are 0s.

When a program detects that the receive data register is full (RDRF = 1), it gets the data from the receive data register by reading SCIxD. The RDRF flag is cleared by reading SCIxS1 while RDRF = 1 and then reading SCIxD.

When polling is used, this sequence is naturally satisfied in the normal course of the user program. If hardware interrupts are used, SCIxS1 must be read in the interrupt service routine (ISR). Normally, this is done in the ISR anyway to check for receive errors, so the sequence is automatically satisfied.

The IDLE status flag includes logic that prevents it from getting set repeatedly when the RxD line remains idle for an extended period of time. IDLE is cleared by reading SCIxS1 while IDLE = 1 and then reading SCIxD. After IDLE has been cleared, it cannot become set again until the receiver has received at least one new character and has set RDRF.

If the associated error was detected in the received character that caused RDRF to be set, the error flags — noise flag (NF), framing error (FE), and parity error flag (PF) — get set at the same time as RDRF. These flags are not set in overrun cases.

If RDRF was already set when a new character is ready to be transferred from the receive shifter to the receive data buffer, the overrun (OR) flag gets set instead the data along with any associated NF, FE, or PF condition is lost.

At any time, an active edge on the RxD serial data input pin causes the RXEDGIF flag to set. The RXEDGIF flag is cleared by writing a "1" to it. This function does depend on the receiver being enabled (RE = 1).

## 14.3.5 Additional SCI Functions

The following sections describe additional SCI functions.

### 14.3.5.1 8- and 9-Bit Data Modes

The SCI system (transmitter and receiver) can be configured to operate in 9-bit data mode by setting the M control bit in SCIxC1. In 9-bit mode, there is a ninth data bit to the left of the MSB of the SCI data register. For the transmit data buffer, this bit is stored in T8 in SCIxC3. For the receiver, the ninth bit is held in R8 in SCIxC3.

For coherent writes to the transmit data buffer, write to the T8 bit before writing to SCIxD.

If the bit value to be transmitted as the ninth bit of a new character is the same as for the previous character, it is not necessary to write to T8 again. When data is transferred from the transmit data buffer to the transmit shifter, the value in T8 is copied at the same time data is transferred from SCIxD to the shifter.

9-bit data mode typically is used in conjunction with parity to allow eight bits of data plus the parity in the ninth bit. Or it is used with address-mark wakeup so the ninth data bit can serve as the wakeup bit. In custom protocols, the ninth bit can also serve as a software-controlled marker.



# A.12.4 SPI

Table A-16 and Figure A-7 through Figure A-10 describe the timing requirements for the SPI system.

Num <sup>1</sup>	С	Rating <sup>2</sup>	Symbol	Min	Max	Unit
1	D	Cycle time Master Slave	t <sub>scк</sub> t <sub>scк</sub>	2 4	2048 —	t <sub>cyc</sub> t <sub>cyc</sub>
2	D	Enable lead time Master Slave	t <sub>Lead</sub>	 1/2	1/2	t <sub>SCK</sub> t <sub>SCK</sub>
3	D	Enable lag time Master Slave	t <sub>Lag</sub> t <sub>Lag</sub>	 1/2	1/2	t <sub>SCK</sub> t <sub>SCK</sub>
4	D	Clock (SPSCK) high time Master and Slave	t <sub>SCKH</sub>	(1/2 t <sub>SCK</sub> )– 25	_	ns
5	D	Clock (SPSCK) low time Master and Slave	t <sub>SCKL</sub>	(1/2 t <sub>SCK</sub> ) – 25	_	ns
6	D	Data setup time (inputs) Master Slave	t <sub>SI(M)</sub> t <sub>SI(S)</sub>	30 30		ns ns
7	D	Data hold time (inputs) Master Slave	t <sub>HI(M)</sub> t <sub>HI(S)</sub>	30 30		ns ns
8	D	Access time, slave <sup>3</sup>	t <sub>A</sub>	0	40	ns
9	D	Disable time, slave <sup>4</sup>	t <sub>dis</sub>	_	40	ns
10	D	Data setup time (outputs) Master Slave	t <sub>SO</sub>	25 25		ns ns
11	D	Data hold time (outputs) Master Slave	t <sub>HO</sub>	10 10		ns ns
12	D	Operating frequency <sup>5</sup> Master Slave	f <sub>op</sub> f <sub>op</sub>	f <sub>Bus</sub> /2048 dc	5 f <sub>Bus</sub> /4	MHz

Table A-10. SFT Electrical Characteristic	Table	A-16.	SPI	Electrical	Characteristic
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<sup>1</sup> Refer to Figure A-7 through Figure A-10.

<sup>2</sup> All timing is shown with respect to 20% V<sub>DD</sub> and 70% V<sub>DD</sub>, unless noted; 100 pF load on all SPI pins. All timing assumes slew rate control disabled and high drive strength enabled for SPI output pins.

<sup>3</sup> Time to data active from high-impedance state.

<sup>4</sup> Hold time to high-impedance state.

<sup>5</sup> Maximum baud rate must be limited to 5 MHz due to pad input characteristics.



NOTES:

- 1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M-1994.
- 2. CONTROLLING DIMENSION: MILLIMETER.
- 3. DATUM PLANE AB IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
- 4. DATUMS T, U, AND Z TO BE DETERMINED AT DATUM PLANE AB.

 $\mathbf{X}$  dimensions to be determined at seating plane ac.

6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE AB.

THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.350.

8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076.

9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

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